- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

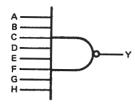
These devices contain a single 8-input NAND gate.

The SN5430, SN54LS30, and SN54S30 are characterized for operation over the full military range of  $-55\,^{\circ}\text{C}$  to  $125\,^{\circ}\text{C}$ . The SN7430, SN74LS30, and SN74S30 are characterized for operation from  $0\,^{\circ}\text{C}$  to  $70\,^{\circ}\text{C}$ .

#### **FUNCTION TABLE**

INPUTS A THRU H	OUTPUT Y
All inputs H One or more inputs L	L H

#### logic diagram

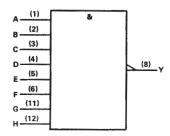


#### positive logic

$$Y = \overline{A \cdot B \cdot C \cdot D \cdot E \cdot F \cdot G \cdot H} \quad \text{or}$$

$$Y = \overline{A} + \overline{B} + \overline{C} + \overline{D} + \overline{E} + \overline{F} + \overline{G} + \overline{H}$$

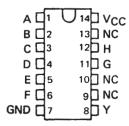
#### logic symbol†



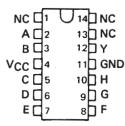
<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

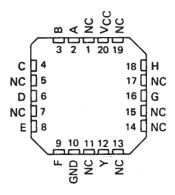
SN5430 . . . J PACKAGE
SN54LS30, SN54S30 . . . J OR W PACKAGE
SN7430 . . . N PACKAGE
SN74LS30, SN74S30 . . . D OR N PACKAGE
(TOP VIEW)



SN5430 . . . W PACKAGE (TOP VIEW)

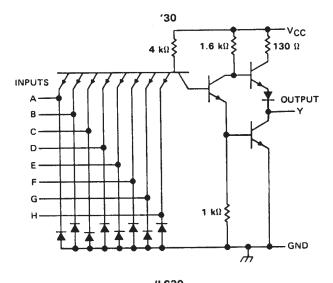


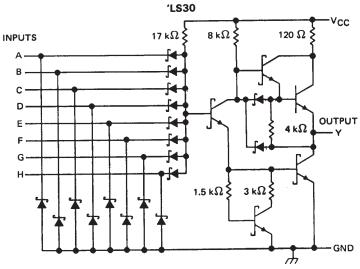
SN54LS30, SN54S30 . . . FK PACKAGE (TOP VIEW)

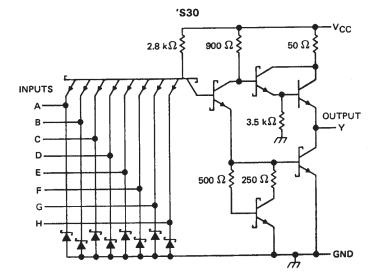


NC - No internal connection

#### schematics (each gate)







Resistor values shown are nominal.



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	,
Input voltage	5.5 V
Operating free-air temperature range: SN5430	−55°C to 125°C
SN7430	0°C to 70°C
Storage temperature range	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

		SN5430		SN7430				
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			٧
VIL	Low-level input voltage			8.0			0.8	V
ЮН	High-level output current			- 0.4			- 0.4	mA
loL	Low-level output current			16			16	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					SN5430	)		SN743	0	UNIT
PARAMETER		TEST CONDI	TIONS I	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V <sub>CC</sub> = MIN,	I <sub>I</sub> = - 12 mA				- 1.5			- 1.5	٧
Voн	V <sub>CC</sub> = MIN,	V <sub>IL</sub> = 0.8 V,	1 <sub>OH</sub> = - 0.4 mA	2.4	3.4		2.4	3.4		V
VOL	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OL</sub> = 16 mA		0.2	0.4		0.2	0.4	٧
l <sub>1</sub>	V <sub>CC</sub> = MAX,	V <sub>i</sub> = 5.5 V				1			1	mA
IIH	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.4 V				40			40	μΑ
I <sub>IL</sub>	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				- 1.6			- 1.6	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX			- 20		- 55	- 18		- 55	mA
Iссн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0			. 1	2		1	2	mA
1CCL	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 4.5 V			3	6		3	6	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	ТҮР	MAX	UNIT
t <sub>PLH</sub>					13	22	ns
tpHL	Any	Y	$R_L = 400 \Omega$ , $C_L = 15 pF$		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range: SN54LS30	-55°C to 125°C
SN74LS30	
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

			SN54LS	30	:	SN74LS	30	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONII
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2	· · · · · · · · · · · · · · · · · · ·		2			٧
VIL	Low-level input voltage			0.7			8.0	٧
ЮН	High-level output current			- 0.4			- 0.4	mA
lOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

					SN54LS	30		SN74LS	30	UNIT
PARAMETER		TEST CONDIT	TONS I	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V <sub>CC</sub> = MIN,	I <sub>1</sub> = - 18 mA				- 1.5			<b>– 1.5</b>	٧
Voн	V <sub>CC</sub> = MIN,	VIL = MAX,	I <sub>OH</sub> = - 0.4 mA	2.5	3.4		2.7	3.4		٧
	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	I <sub>OL</sub> = 4 mA		0.25	0.4			0.4	V
VOL	V <sub>CC</sub> = MIN,	V <sub>1H</sub> = 2 V,	I <sub>OL</sub> = 8 mA					0.25	0.5	
. 4	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mΑ
ΊΗ	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 2.7 V				20			20	μА
ИL	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0.4 V				- 0.4			- 0.4	mA
I <sub>OS</sub> §	V <sub>CC</sub> = MAX			- 20		- 100	- 20		- 100	mA
Іссн	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 0			0.35	0.5		0.35	0.5	mA
ICCL	V <sub>CC</sub> = MAX,	V <sub>I</sub> = 4.5 V			0.6	1.1		0.6	1.1	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	Any	V	$R_L = 2 k\Omega$ , $C_L = 15 pF$		8	15	ns
tPHL	Ally	<b>'</b>	N 2 ktz,		13	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



 $<sup>\</sup>ddagger$  All typical values are at  $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ 

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54S30	-55°C to 125°C
SN74S30	
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

#### recommended operating conditions

			SN54S3	10		SN74S	30	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			٧
VIL	Low-level input voltage			0.8			8.0	٧
Іон	High-level output current			- 1			- 1	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN54S30	SN74S30	UNIT
PARAMETER	TEST CONDITIONS †	MIN TYP\$ MAX	MIN TYP‡ MAX	ONT
VIK	V <sub>CC</sub> = MIN, 1 <sub>1</sub> = -18 mA	-1.2	-1.2	٧
Voн	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = -1 mA	2.5 3.4	2.7 3.4	٧
VOL	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 20 mA	0.5	0.5	٧
11	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V	1	1	mA
ΙΗ	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V	50	50	μΑ
IIL	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V	-2	-2	mA
IOS§	V <sub>CC</sub> = MAX	-40 -100	-40 -100	mA
Іссн	V <sub>CC</sub> = MAX, V <sub>i</sub> = 0	3 5	3 5	mA
¹ccL	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V	5.5 10	5.5 10	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

#### switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN TY	P MAX	UNIT	
<sup>t</sup> PLH			D - 200 O	CL = 15 pF		4 6	ns
tPHL.			$R_L = 280 \Omega$ ,	CL 1991	4.	5 7	ns
t <sub>PLH</sub>	Any	Y		0 - 50 - 5	5.	5	ns
<sup>t</sup> PHL	į	i	$R_L = 280 \Omega$ ,	C <sub>L</sub> = 50 pF	6.	5	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

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## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
5962-9679201Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
JM38510/30009SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	
JM38510/30009SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	
JM38510/30009SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	
JM38510/30009SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	
M38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
M38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
M38510/30009SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	
M38510/30009SCA	ACTIVE	CDIP	J	14	25	TBD	A42	N / A for Pkg Type	
M38510/30009SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	
M38510/30009SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	
SN5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74LS30NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN5430, SN54LS30, SN54LS30-SP, SN54S30, SN7430, SN74LS30, SN74S30:

Catalog: SN7430, SN74LS30, SN54LS30, SN74S30

Military: SN5430, SN54LS30, SN54S30



23-Mar-2012

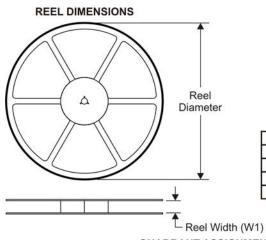
• Space: SN54LS30-SP

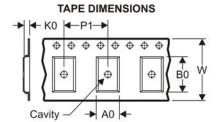
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application



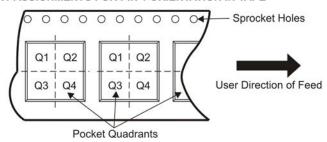
## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS30DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS30NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

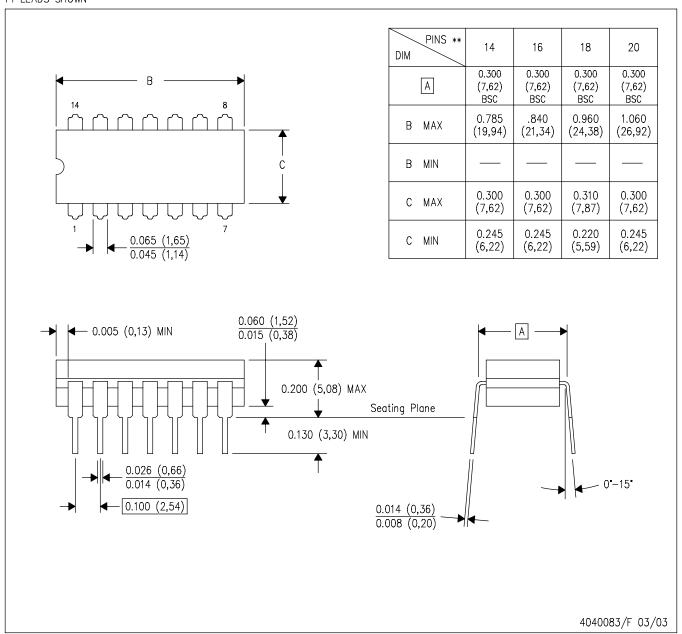




\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS30DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS30NSR	SO	NS	14	2000	346.0	346.0	33.0

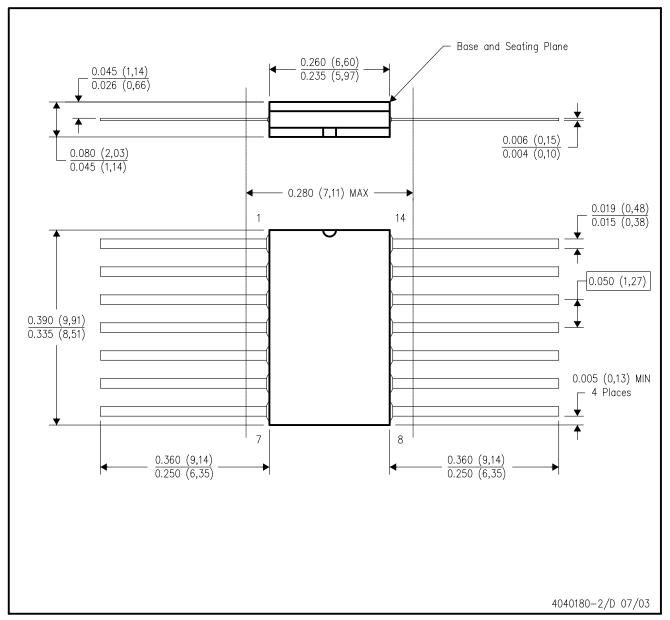
#### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# W (R-GDFP-F14)

# CERAMIC DUAL FLATPACK



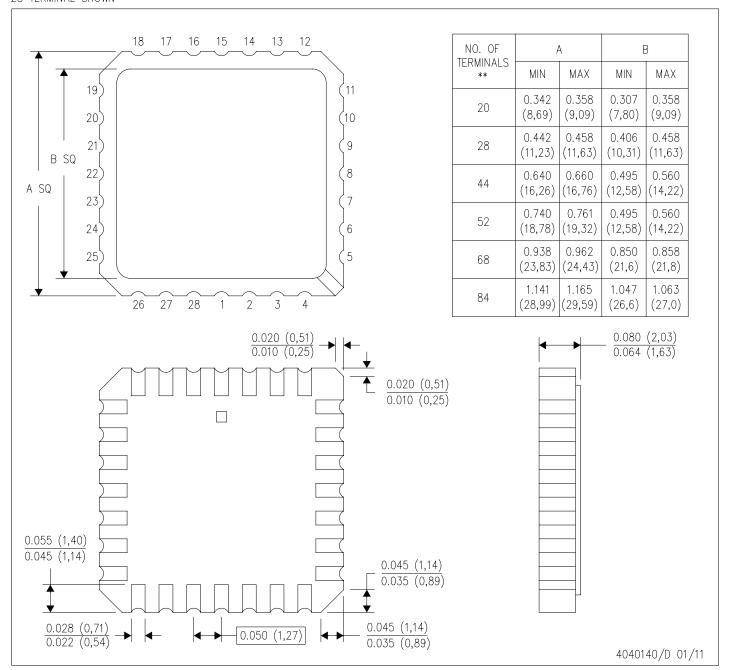
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



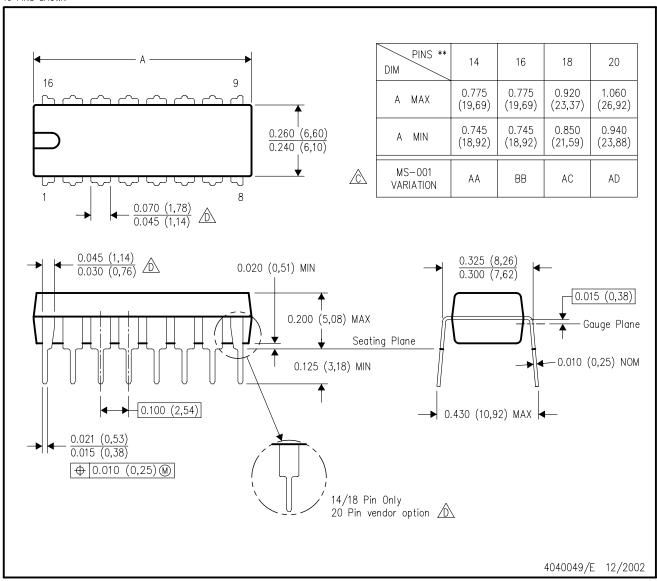
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

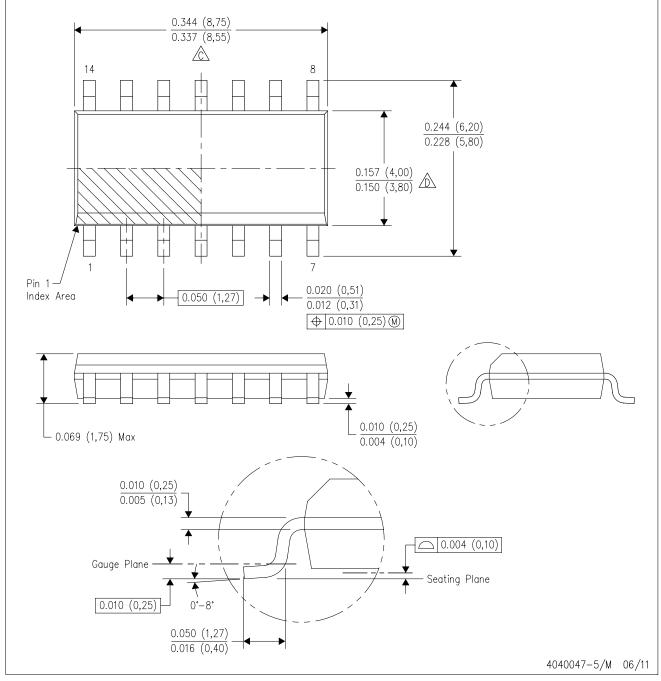


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE

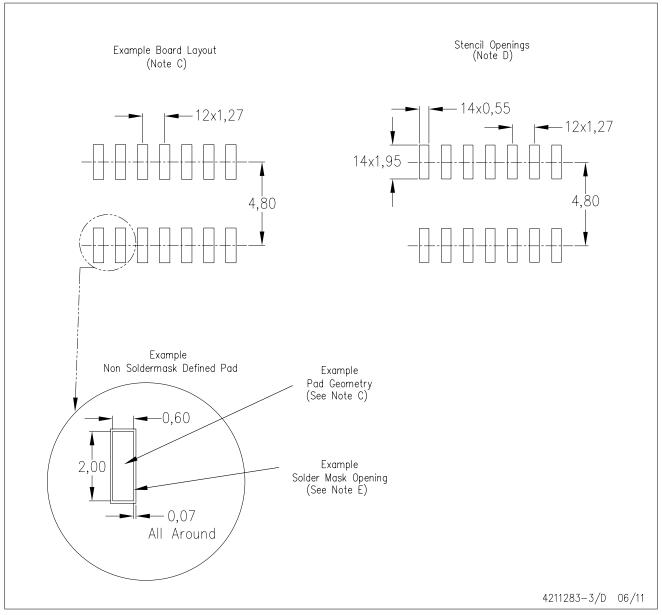


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

# PLASTIC SMALL OUTLINE



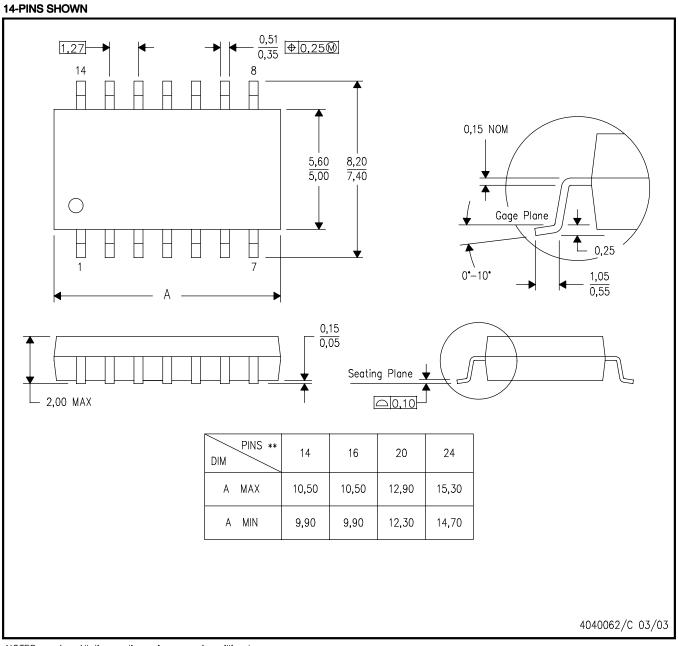
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE



- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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